XL-IRM-V838M3-TR 技术数据表 **Technical Data Sheet**

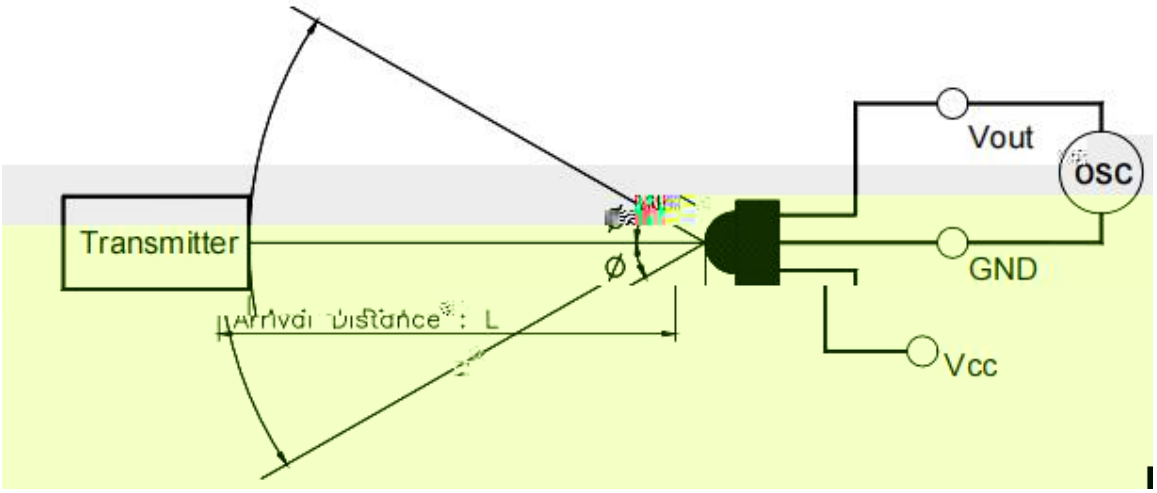
Electric haracteristics

Absolute Maximum Ratings Ta=25

Parameter	Symbol	Rating	Unit
Supply voltage	VCC	-0.2~0.6	V
Ope			

২ Application cir ϑ D

3. Receiving angle testing method



غ عمم ü h Indicates horizontal and vertical directions

ۑ 200 ± 50Luxض ۑ

Note Ambient light source : Detecting surface illumination shall be irradiate 200±50Lux under ordinary white fluorescence lamp without high frequency lighting

典型特性曲线

Typical Characteristics Curves

Applicable data formats

Item	Symbol	Time
Maximum Data word length	-	Max. 100ms
Minimum burst length	tBurst	300us
Minimum gap time after each burs	tGap	300us
Minimum pause time in the data stream	tPause	Min. 25ms
Required data pause time	tPause > (Data word length/3) +18.5ms	

Data Signal diagram

- ESD External Application Circuit - Power Noise reduction & ESD Protection

Application for power supply ripple suppression

可靠性试验

Reliability Test Items And Conditions

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	Ð			
	260 ±5 Ì ę	5 γ ṗ	20	20
ڜ	100PF 1.5KΩ, ㄱ4KV, ㇀		20	20
⌟	10-50HZ/1min 1.5mm X Y Z/30min	30№	20	20
Ũ	85 ±2	240	20	20
㇀ Ũ	-20 ±2	240	20	20
Ũ	85 85%	240	20	20
㇀	㇀ -20 30 +85 30	10	20	20
	2.5N ę 2		20	20

Pin Configuration

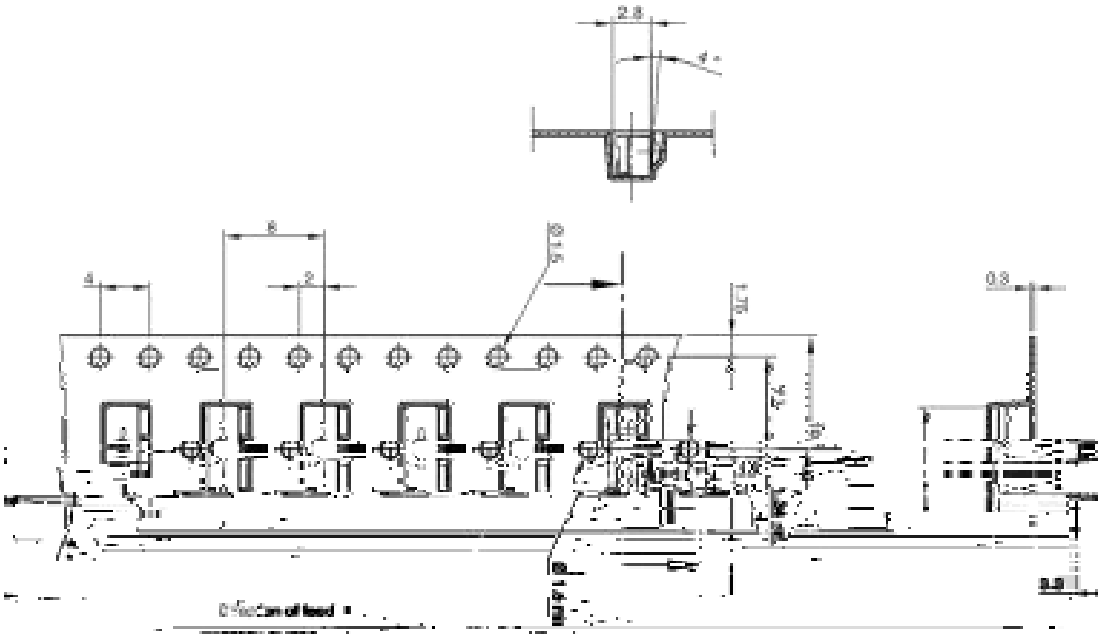
1. Gnd
2. Gnd
3. Out
4. Vcc

包装(1)

Packaging(1)

载带与圆盘尺寸 Belt and disk dimensions

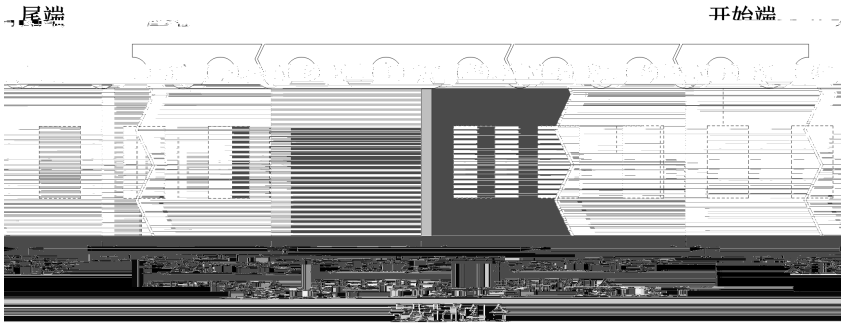
Taping Version: R1

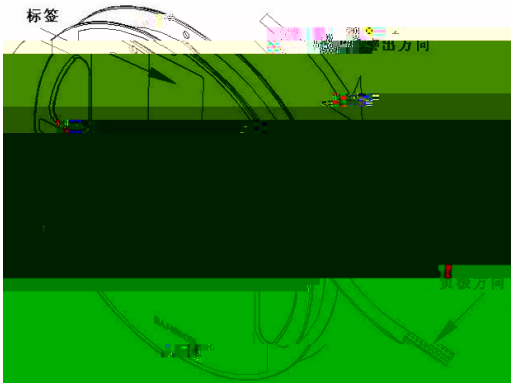


:

1. ㄚβ (mm)
1. Size unit is mm (mm).
2. Ě ±0.1mm
   The dimensional tolerance is ± 0.1mm.

圆盘及载带卷出方向及空穴规格 Disk and carrier belt direction of roll and hole dimensions





包装（2）

Packaging (2)

Moisture Proo

焊接指导（1）

Guideline for Soldering (1)

1. 使用烙铁人手焊接

Hand Soldering

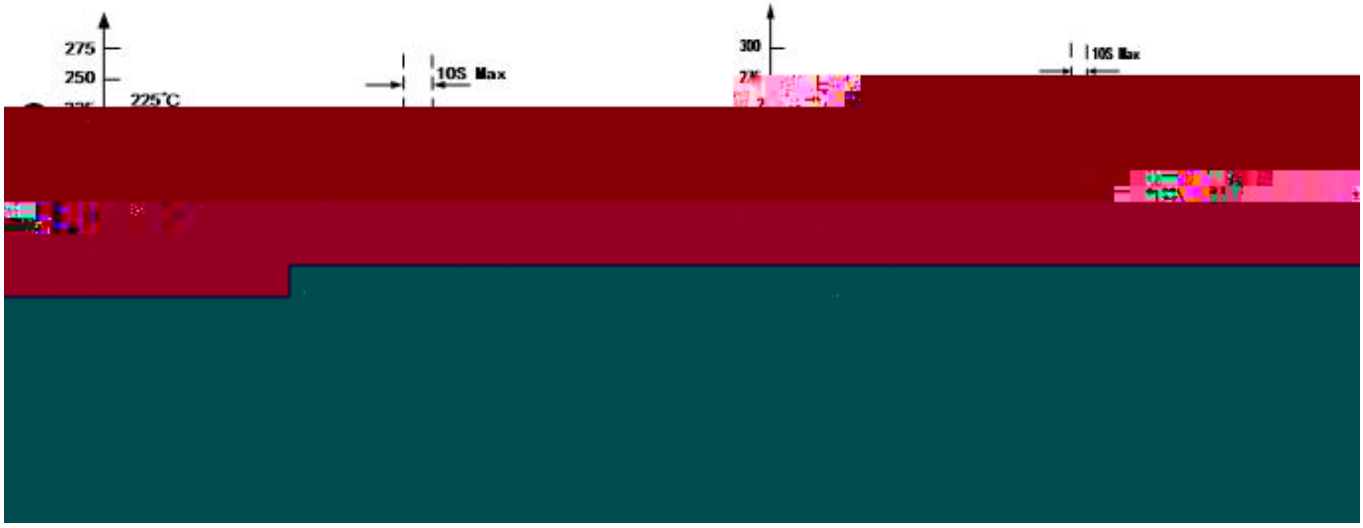
7 ضي ḱ ġ ’ ą ą w ɣ 30W Ḡ ضي
300 ɣ 7 3 ƀ
LED ج شخ

Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300 while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

Be careful because the damage of the product is often started at the time of the hand soldering.

2. 回流焊接： ą ɣ عج يح

Reflow Soldering: Use the conditions shown in the under Figure ofPb-Free Reflow Soldering.



· عج 7

Reflow soldering should not be done more than two times.

· عجضي ٦ LED ٧ K ٧ ٦ Z

Stress on the LEDs should be avoided during heating in soldering process.

· ضي U ج ⌈ U 'P ٱ ٢

After soldering, do not deal with the product before its temperature drop down to room temperature.

· ج g └ضي240 /6S

The recommended maximum welding temperature for the product is 240 /6s

焊接指导（2）

Guideline for Soldering (2)

[redacted]

使用注意事项（1）

Precautions (1)

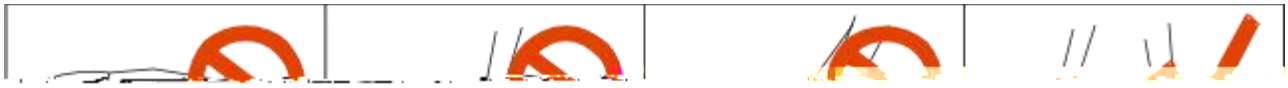
使用注意事項（ ）

（ ）

3. 其他事項:

Others

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED